

1.Description

These devices are well suited for low voltage and battery powered applications where low in-line power loss and fast switching are required.

2.2Features

- High power and current handling capability
- High performance trench technology for extremely low $R_{DS(ON)}$

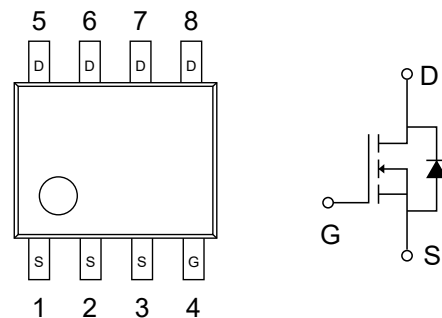
2.1Features

- $V_{DS(V)}=30V$
- $I_D=12.5A$
- $R_{DS(ON)}<7.8m\Omega(V_{GS}=10V)$
- $R_{DS(ON)}<9.9m\Omega(V_{GS}=4.5V)$

3.Pinning information

Pin	Symbol	Description
4	G	GATE
1,2,3	S	SOURCE
5,6,7,8	D	DRAIN

SOP-8



4.Absolute Maximum Ratings $T_A=25^{\circ}C$ unless otherwise noted

Parameter	Symbol	Value	Units
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GSS}	± 20	V
Drain Current – Continuous	I_D	12.5	A
– Pulsed (Note 1a)		50	
Power Dissipation for Single Operation (Note 1a)	P_D	2.5	W
		1.2	
		1	
Operating and Storage Junction Temperature Range	T_J, T_{STG}	-55 to 150	$^{\circ}C$



5. Thermal Characteristics

Parameter	Symbol	Rating	Units
Thermal Resistance, Junction-to-Ambient (Note 1a)	$R_{\theta JA}$	50	°C/W
Thermal Resistance, Junction-to-Case (Note 1)	$R_{\theta JC}$	25	°C/W



6. Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

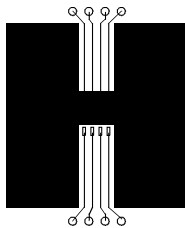
Parameter	Symbol	Conditions	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D=250\mu\text{A}$, $V_{GS}=0\text{V}$	30			V
Breakdown Voltage Temperature Coefficient	$\frac{\Delta BV_{DSS}}{\Delta T_J}$	$I_D=250\mu\text{A}$ Referenced to 25°C		25		mV/ $^\circ\text{C}$
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=24\text{V}$, $V_{GS}=0\text{V}$			1	μA
		$V_{DS}=24\text{V}$, $V_{GS}=0\text{V}$, $T_J=55^\circ\text{C}$			10	μA
Gate-Body Leakage	I_{GSS}	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$			± 100	nA
On Characteristics (Note 2)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	1	2	3	V
Gate Threshold Voltage Temperature Coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	$I_D=250\mu\text{A}$ Referenced to 25°C		-4.9		mV/ $^\circ\text{C}$
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10\text{V}$, $I_D=12.5\text{A}$		7.8	9.5	m Ω
		$V_{GS}=4.5\text{V}$, $I_D=10.5\text{A}$		9.9	13	
On-State Drain Current	$I_{D(on)}$	$V_{GS}=10\text{V}$, $V_{DS}=5\text{V}$	25			A
Forward Transconductance	g_{FS}	$V_{DS}=15\text{V}$, $I_D=12.5\text{A}$		64		S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=15\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$		1620		pF
Output Capacitance	C_{oss}			380		pF
Reverse Transfer Capacitance	C_{rss}			160		pF
Gate Resistance	R_G	$V_{GS}=15\text{mV}$, $f=1\text{MHz}$		1.3		Ω
SWITCHING PARAMETERS (Note 2)						
Turn-On Delay Time	$t_{D(on)}$	$V_{DD}=15\text{V}$, $I_D=1\text{A}$ $V_{GS}=10\text{V}$, $R_{GEN}=6\Omega$		10	19	ns
Turn-On Rise Time	t_r			5	10	ns
Turn-Off Delay Time	$t_{D(off)}$			27	43	ns
Turn-Off Fall Time	t_f			15	27	ns



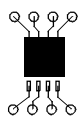
Total Gate Charge	Q _g	V _{DS} =15V, I _D =12.5A V _{GS} =5V		16	23	nC
Gate–Source Charge	Q _{gs}			5		nC
Gate–Drain Charge	Q _{gd}			5.8		nC
Drain–Source Diode Characteristics and Maximum Ratings						
Maximum Continuous Drain–Source Diode Forward Current	I _S				2.1	A
Drain–Source Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =2.1A(Note 2)		0.73	1.2	V
Diode Reverse Recovery Time	t _{rr}	I _F =12.5A, d _I F/d _t =100A/μs		28		nS
Diode Reverse Recovery Charge	Q _{rr}			18		nC

Notes:

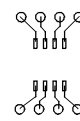
1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.



a) 50° C/W when mounted on a 0.5 in² pad of 2 oz. copper.



b) 105° C/W when mounted on a 0.02 in² pad of 2 oz. copper.



c) 125° C/W when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%



7.1 TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

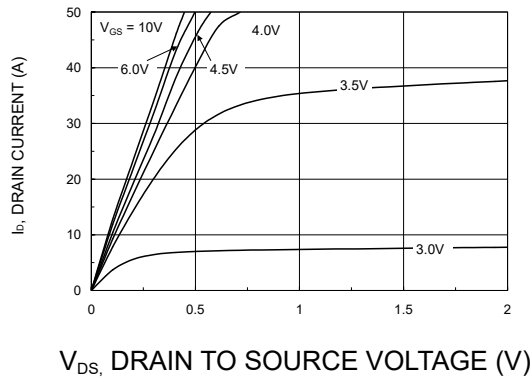


Fig 1: On-Region Characteristics.

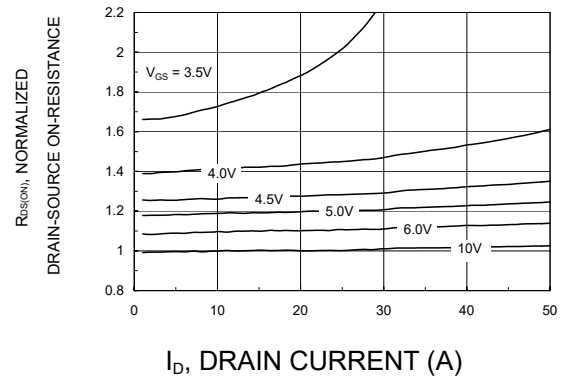


Figure 2: On-Resistance Variation with Drain Current and Gate Voltage.

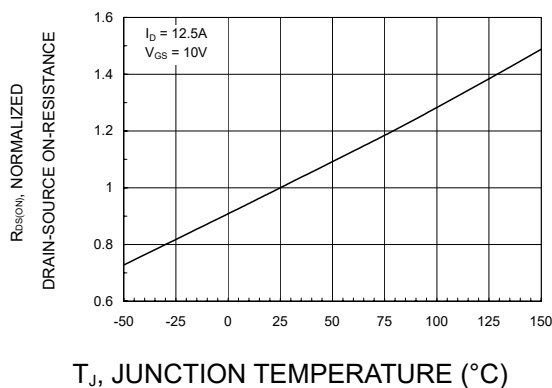


Figure 3: On-Resistance Variation with Temperature.

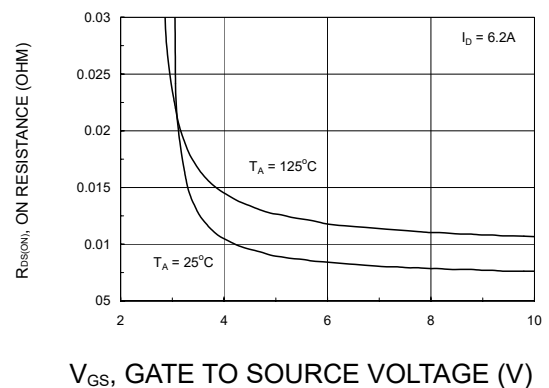


Figure 4: On-Resistance Variation with Gate-to-Source Voltage.

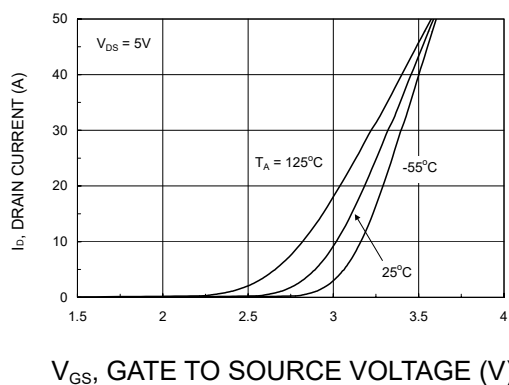


Figure 5: Transfer Characteristics.

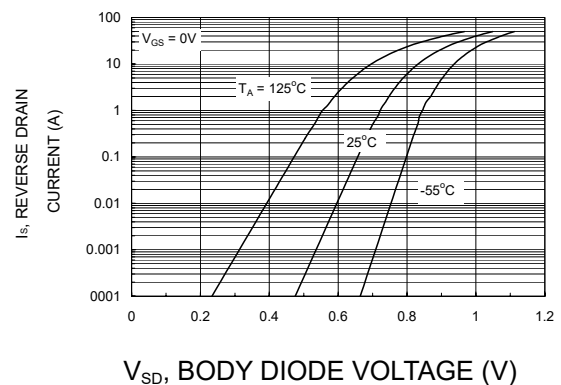


Figure 6: . Body Diode Forward Voltage Variation with Source Current and Temperature.



7.2 TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

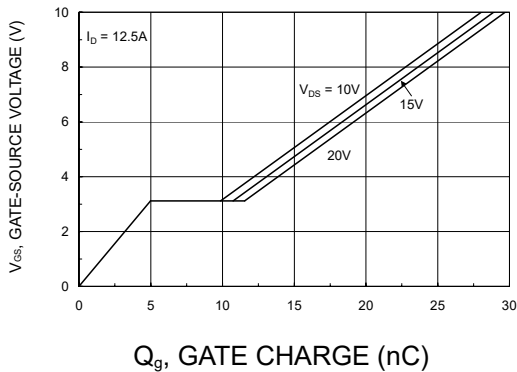


Figure 7: Gate-Charge Characteristics

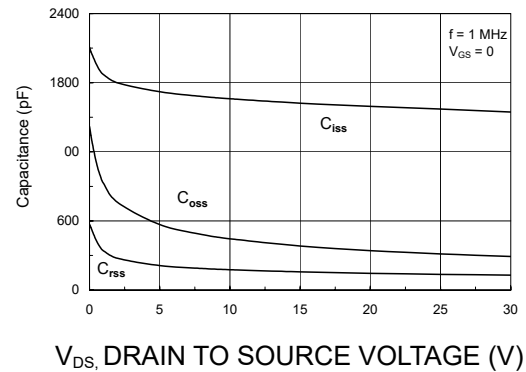


Figure 8: Capacitance Characteristics

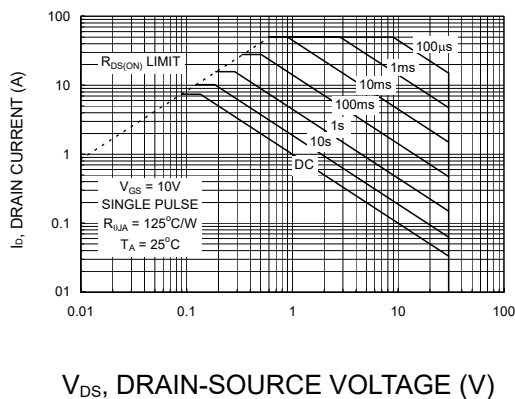


Figure 9: Maximum Safe Operating Area.

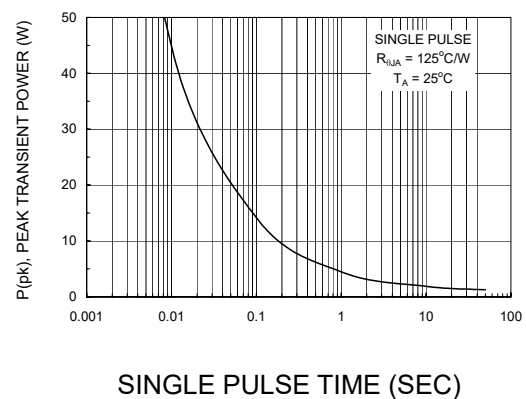


Figure 10: Single Pulse Maximum Power Dissipation.

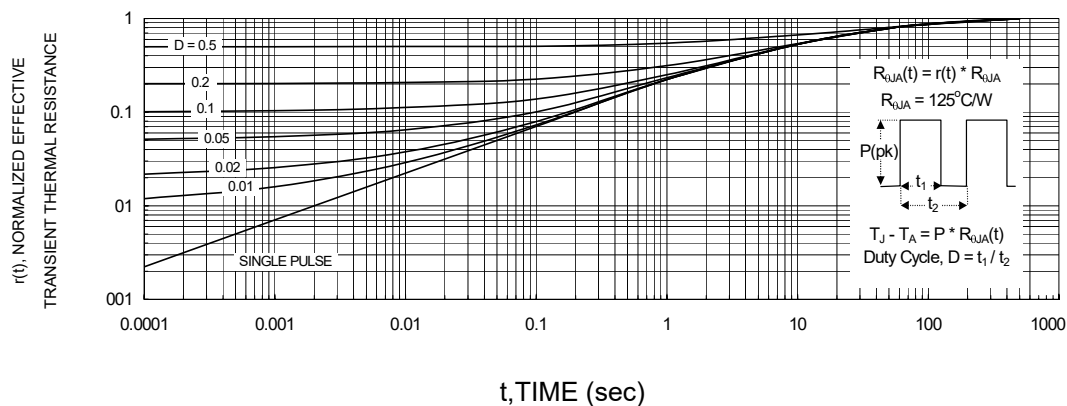
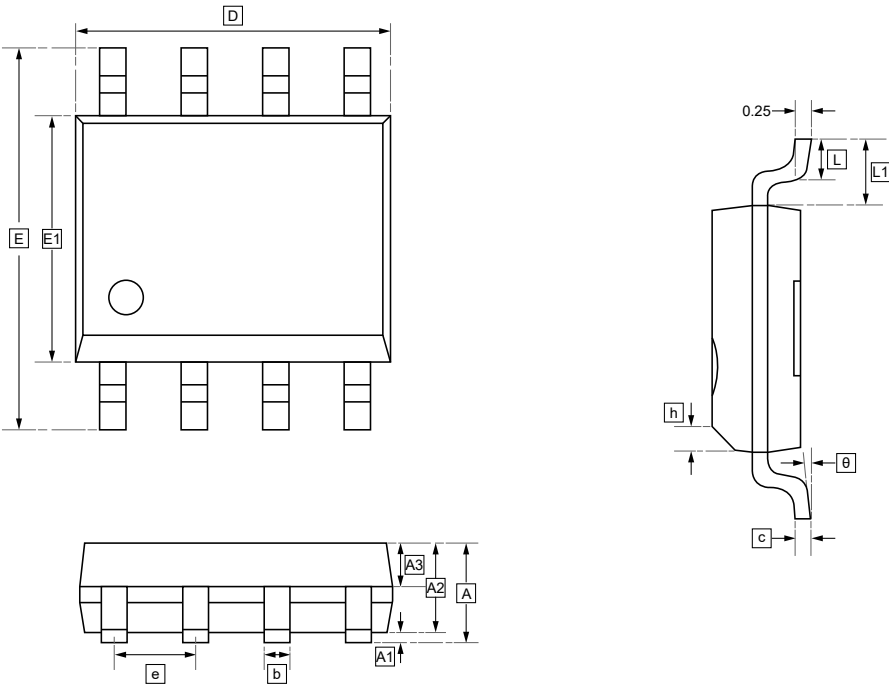


Figure 11: Transient Thermal Response Curve.



8.SOP-8 Package Outline Dimensions



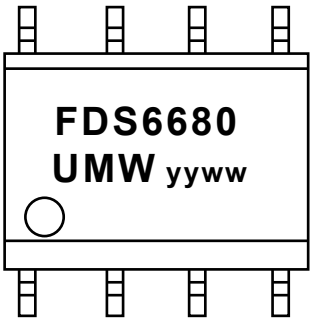
DIMENSIONS (mm are the original dimensions)

Symbol	A	A1	A2	A3	b	c	D	E	E1	e	h	L
Min	-	0.05	1.30	0.60	0.39	0.20	4.80	5.80	3.80	1.24	0.30	0.50
Max	1.75	0.20	1.50	0.70	0.47	0.24	5.00	6.20	4.00	1.30	0.50	0.80

Symbol	L1	θ
Min	1.00	0°
Max	1.10	8°



9.Ordering information



yy: Year Code
ww: Week Code

Order Code	Package	Base QTY	Delivery Mode
UMW FDS6680A	SOP-8	3000	Tape and reel



10.Disclaimer

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